SEMESTER VI

	MICROWAVE ENGINEERING

Module	Content	No. of Lectures
1	**Introduction:** RF and microwave spectrum, historical background, application of RF and Microwave Impedance Matching–Unknown impedance measurement using shift in minima technique and impedance matching using single and double stub matching.	8
2	**Microwave waveguides and components**: Rectangular waveguide and circular waveguide, mode structure, cutoff frequency, wall current, attenuation; microwave cavities – rectangular cavity resonator, Q factor power divider, scattering matrix and transmission matrix, attenuator, phase shifter, directional coupler, Bethe hole coupler, magic tee, hybrid ring, circulator, isolator, Ferrite Devices	10
3	**Planar structures:** Strip line, microstrip line, coplanar structure **Microwave Tubes:** Limitations of conventional tubes, Multicavity Klystron, Reflex Klystron, Magnetron, Travelling Wave Tube, Backward Wave Oscillator Semiconductor Microwave Devices – Tunnel diode, Gunn diode and thei waveguide mounts	10
4	**Avalanche diodes:** IMPATT, TRAPATT, Microwave bipolar transistor, heterojunction bipolar transistor. **Microwave field effect transistor:** JFET, MOSFET, MESFET **Applications of microwave:** Industrial Applications of microwave.	8
5	**Microwave Measurement:** VSWR measurement, power measurement, impedance measurement, frequency Measurement Equivalent RF circuit parameters Low pass filter, high pass filter, band pass filter, RF amplifier.	6

Text Books/References books:

1. Golio M, Golio J (2008) The RF and Microwave Handbook. CRC Press.
2. Pozar DM (2005) Microwave Engineering. John Wiley & Sons.
3. Hong JS, Lancaster MJ (2001) Microstrip Filters for RF/Microwave Applications. John Wiley & Sons.

List of experiments:

1. To measure the frequency and wavelength using slotted line section and frequency meter.
2. To measure the Isolation and Insertion loss of Isolator and Circulator.
3. To study E-plane, H-plane and Magic Tee.
4. To measure Coupling Factor, Directivity and Isolation of directional coupler.
5. To measure VSWR and Reflection coefficient of different loads.
6. To study the characteristics of Klystron and Gunn diode.

7. Simulation of Transmission line: Waveguide and Coaxial line.
8. Simulation of directional coupler.
9. Simulation of E-plane and H-plane Tee.
10. Study of micro strip line and LPF using HFSS Software.
11. Study of BPF using HFSS Software.

	VLSI DESIGN

Module	**Content**	**No. of Lectures**
1	**Introduction:** Review of MOSFET characteristics, scaling and small-geometry effects, and MOSFET capacitances. MOS resistor, MOS current source, current mirror circuits. MOS voltage source, linear voltage and current converters.	**6**
2	**CMOS operational amplifier (OPAMP) design:** Differential amplifier, level shifter, source follower, output stage voltage and power amplifiers. Cascode OP-AMP. Compensation techniques. **Analog Filters:** Switched capacitor (SC) fundamentals, first order SC circuits, second-order SC circuits and cascade design. Analog to digital and digital to analog converters, speed of conversion and over sampling issues. **VLSI Interconnects:** Distributed RC model, transmission line model. Future inter connect technologies.	**14**
3	**Digital VLSI Circuit Design:** MOS inverters, CMOS inverter, state characteristics, switching characteristics, power dissipation issues. **CMOS logic gates:** NAND, NOR, XOR, CMOS logic design of half and full adders. CMOS transmission gates, pseudo-nMOS, domino logic gates.	**9**
4	**Sequential MOS Logic Circuits:** The SR latch circuit, clocked latch and flip-flop, CMOS D-latch and edge-triggered circuits, Schmitt trigger circuit, Comparator. **Dynamic Logic Circuits:** Pass transistor logic, synchronous dynamic circuit techniques.	**8**
5	**Semiconductor Memories:** ROM circuits, SRAM circuits, DRAM circuits, drivers and buffers, Buffer scaling and design issues	**5**

Text Books/Reference books: